

3. A process according to Claim 4, wherein the mold has a temperature of 150°C.

4. (Amended) A process for manufacturing a covering or trim part with a directly molded-on carrier, comprising:

placing a decor part into an at least two-part injection mold;

closing the mold, thereby cutting the decor part to precise contours in the injection mold by shearing off an outer portion of the decor part;

pressing the cut decor part by injecting a molding compound against a surface of the decor part opposite at least one injection opening;

connecting the injection molding compound with the decor part during hardening of the molding compound, wherein the molding compound forms the carrier; and

opening the injection mold and removing the covering or trim part and molded-on carrier,

wherein the decor part is a veneer wood layer.

8. (Amended) A process for manufacturing a covering or trim part with a directly molded-on carrier, comprising:

placing a decor part into an at least two-part injection mold;

closing the mold, thereby cutting the decor part to precise contours in the injection mold by shearing off an outer portion of the decor part;

pressing the cut decor part by injecting a molding compound against a surface of the decor part opposite at least one injection opening;

connecting the injection molding compound with the decor part during hardening of the molding compound, wherein the molding compound forms the carrier; and

opening the injection mold and removing the covering or trim part and molded-on carrier,

wherein the décor part comprises a sheet metal part and the process further comprises:

D<sup>2</sup> applying a coupling layer to the backside of the sheet metal part;

and

heating or activating the coupling layer with the injection molding compound.

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10. (Amended) A process according to Claim 4, further comprising embedding fastening elements for the covering or trim part in the injection molding compound.

11. (Amended) A process for manufacturing a covering or trim part with a directly molded-on carrier, comprising:

D<sup>3</sup> placing a decor part into an at least two-part injection mold;

closing the mold, thereby cutting the decor part to precise contours in the injection mold by shearing off an outer portion of the decor part;

pressing the cut decor part by injecting a molding compound against a surface of the decor part opposite at least one injection opening;

connecting the injection molding compound with the decor part during hardening of the molding compound, wherein the molding compound forms the carrier; and

opening the injection mold and removing the covering or trim part and molded-on carrier,

wherein the closing of the mold comprises simultaneously cutting and stamping the decor part.

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Applicant's Remarks are set forth starting on the following page.